

II. SPECIFICATION AMENDMENTS

Please delete the paragraph starting on page 1, line 8 through line 26 and replace with the following replacement paragraph:

Various different cable structures are utilised in the construction of electronic appliances. As the frequencies of operation increase, there are higher requirements set for the cable structures to be used, in order to prevent attenuation caused by said cable structures. At present, in the structures of electronic appliances, there is generally applied the so-called multilayer technique, which is based either on the HTCC technique (High Temperature Cofired Ceramics) or on the LTCC technique (Low Temperature Cofired Ceramics). With both manufacturing methods, the produced structures consist of several green tapes, with a thickness of about 100 μm , which are positioned one on top of the other. Prior to thermal treatment, the material still is soft, so that in the green tapes, there can be made cavities of desired shapes. Likewise, at desired spots, there can be silk-screened various electrically passive elements. The elastic layers are laminated together by means of pressure. In order to prevent the lamination pressure from collapsing the structure that contains various cavities, the pressurising must be carried out according to a so-called unaxial method. This means that the pressure is directed to the object only in the direction of the axis z of said object. Finally the ~~created~~resultant structure is burnt, in the case of LTCC at 850 degrees and in the case of HTCC at 1,600 degrees. In the elements to be produced, at the cavities there are made perforations through which the excess pressure created in the burning process can be let out.

On page 1, between lines 26 and 27, please insert the following heading:

--SUMMARY OF THE INVENTION--

Please delete the paragraph starting on page 7, line 33 through page 8, line 8 and replace with the following replacement paragraph:

In the embodiment illustrated in figure 6, the transmission cable structure is composed of at least two elements 62 and 63. The contact surface of the elements 62 and 63, illustrated by the dotted line 66, is chosen to be the best possible with respect to the manufacturing of the product. It may be located at the illustrated point, in which case it is level with the surface of the support element 65, which in the drawing is illustrated by the dotted line 66. In this embodiment, the shape of the support element is inwardly curved. The support element 65 constitutes part of the element 63. Also in this embodiment only a small part of the electric field is emitted from the signal cable 60 towards the around-ground cable 61, which in figure 6 is illustrated by the power lines 64, proceeds in the dielectric material of the support element. Likewise, also in this embodiment the attenuation of an inverted microstrip cable according to the invention is low in comparison with a corresponding prior art transmission cable.